

JEDEC
SOLID STATE PRODUCT
OUTLINES

THIS REGISTERED OUTLINE HAS BEEN PREPARED BY THE JEDEC JC-11
COMMITTEE AND REFLECTS A PRODUCT WITH ANTICIPATED USAGE
IN THE ELECTRONICS INDUSTRY; CHANGES ARE LIKELY TO OCCUR.

TITLE:
STACKED TSOP II PACKAGE FAMILY (2 HIGH)

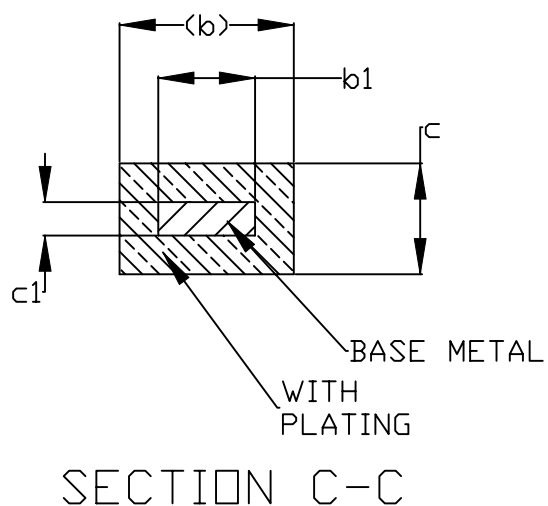
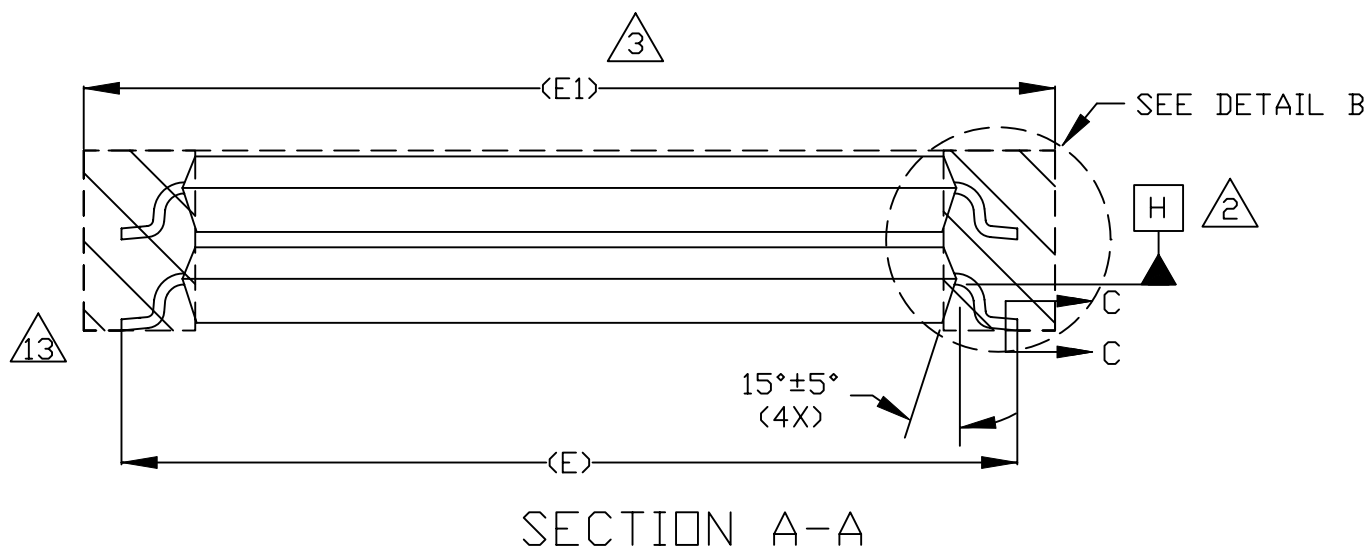
R-PDSO-G/ STACKED TSOP II

ISSUE:
A

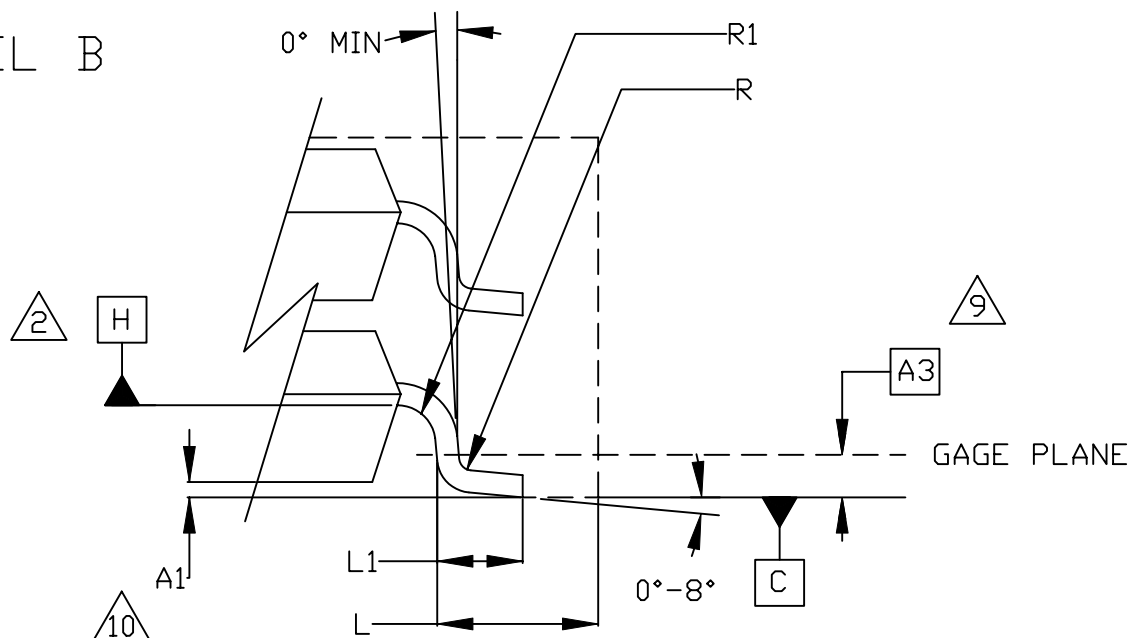
DATE:
2/03

MO-238

SHEET:
1 OF 4



DETAIL B



S Y M B O L	COMMON DIMENSIONS			N O T E
	ALL DIMENSIONS IN MILLIMETERS			
	MIN	NOM	MAX	
A1	0.05	—	0.15	10
A3	0.25 BASIC			
c	0.12	—	0.21	7
c1	0.12	0.15	0.16	7
E	11.76 BASIC			4,6
E2	10.16 BASIC			
L1	0.40	0.50	0.60	
R	0.12	—	0.35	
R1	0.12	—	—	
NOTE	1,5			
REF	11-635			
ISSUE	A			

S Y M B O L	VARIATIONS						N O T E
	ALL DIMENSIONS IN MILLIMETERS						
	AA			AB			
	MIN	NOM	MAX	MIN	NOM	MAX	
A	—	—	2.60	—	—	2.60	9
b	0.30	—	0.45	0.22	—	0.38	7,11
b1	0.30	0.35	0.40	0.22	.30	0.33	7,11
D	22.22 BASIC			22.22 BASIC			4,6
D1	—	—	22.80	—	—	22.80	
ZD	0.71 REF			0.71 REF			
E1	—	—	12.75	—	—	12.75	
e	0.80 BASIC			0.65 BASIC			
L	0.40	—	1.40	0.40	—	1.20	9
N	—	54	—	—	66	—	12
	TOLERANCES OF FORM AND POSITION						
aaa	—	0.20	—	—	0.12	—	
bbb	—	0.10	—	—	0.10	—	
NOTE	1, 5			1, 5			
REF	11-635			11-635			
ISSUE	A			A			

NOTES:

- 1 DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M-1994.
- 2 DATUM PLANE H COINCIDENT WITH BOTTOM OF LEAD, WHERE LEAD EXITS BODY.
- 3 TO BE DETERMINED AT SEATING PLANE C.
- 4 DATUMS A AND B TO BE DETERMINED AT DATUM H.
- 5 ALL DIMENSIONS IN MILLIMETERS.
- 6 DIMENSION D AND E2 ARE DETERMINED AT DATUM H. DIMENSION D DOES NOT INCLUDE MOLD PROTRUSIONS OR GATE BURRS. MOLD PROTRUSIONS AND GATE BURRS SHALL NOT EXCEED 0.15 mm PER SIDE. DIMENSION E2 DOES NOT INCLUDE INTERLEAD MOLD PROTRUSIONS. INTERLEAD MOLD PROTRUSIONS SHALL NOT EXCEED 0.25 mm PER SIDE.
- 7 THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 mm AND 0.25 mm FROM THE LEAD TIP.
- 8 THE LEAD #1 IDENTIFIER AND LEAD NUMBERING CONVENTION SHALL CONFORM TO JEDEC PUBLICATION 95, SECTION 4.3, SPP-012. DETAILS OF LEAD #1 IDENTIFIER ARE BE OPTIONAL BUT MUST LOCATED WITHIN THE ZONE INDICATED. THE LEAD #1 IDENTIFIER MAY BE EITHER A MOLDED OR A MARKED FEATURE.
- 9 STACKED PACKAGE ENVELOPE. EXACT DESIGN OF THIS FEATURE IS OUTSIDE THE SCOPE OF THIS DOCUMENT.
- 10 A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
- 11 DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION/INTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD TO BE WIDER THAN THE MAXIMUM b DIMENSION BY MORE THAN 0.13 mm. DAMBAR INTRUSION SHALL NOT CAUSE THE LEAD TO BE NARROWER THAN THE MINIMUM b DIMENSION BY MORE THAN 0.07 mm.
- 12 N IS THE MAXIMUM NUMBER OF LEADS.
- 13 BOUNDED AREA CONTAINS VERTICAL INTERCONNECT BETWEEN THE UPPER AND LOWER TSOP II DEVICES. TSOP TO TSOP INTERCONNECT DETAIL IS OUTSIDE OF THE SCOPE OF THIS OUTLINE.